



**PNPN Silicon, Reverse-Blocking,
Power Triode Thyristors**
Qualified per MIL-PRF-19500/108

Qualified Levels:
JAN and JANTX

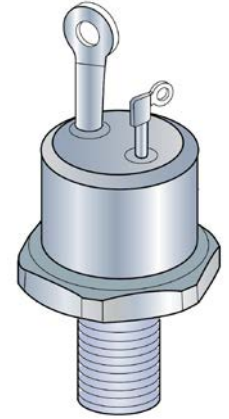
DESCRIPTION

This silicon controlled rectifier device is military qualified up to a JANTX level for high-reliability applications.

Important: For the latest information, visit our website <http://www.microsemi.com>.

FEATURES

- JEDEC registered 2N682, 2N683, 2N685, and 2N687 – 2N692.
- JAN and JANTX qualifications are available per MIL-PRF-19500/108.
- RoHS compliant versions available (commercial grade only).



**TO-208 / TO-48
Package**

APPLICATIONS / BENEFITS

- A general purpose, reverse-blocking thyristor.

MAXIMUM RATINGS

Parameters/Test Conditions	Symbol	Value	Unit
Junction Temperature	T _J	-65 to +125	°C
Storage Temperature	T _{STG}	-65 to +150	°C
Gate Voltage (Peak Total Value)	V _{GM}	5	V(pk)
Maximum Average DC Output Current ⁽¹⁾	I _O	16	A
Non-repetitive Peak On-State Current ⁽²⁾ @ t = 7 ms	I _{TSM}	150	A

- Notes:**
1. This average forward current is for a maximum case temperature of +65 °C, and 180 electrical degrees of conduction.
 2. Surge rating is non-recurrent and applies only with device in the conducting state. The peak rate of surge current must not exceed 100 amperes during the first 10 μs after switching from the off (blocking) state to the on (conducting) state. This time is measured from the point where the thyristor voltage has decayed to 90 percent of its initial blocking value.

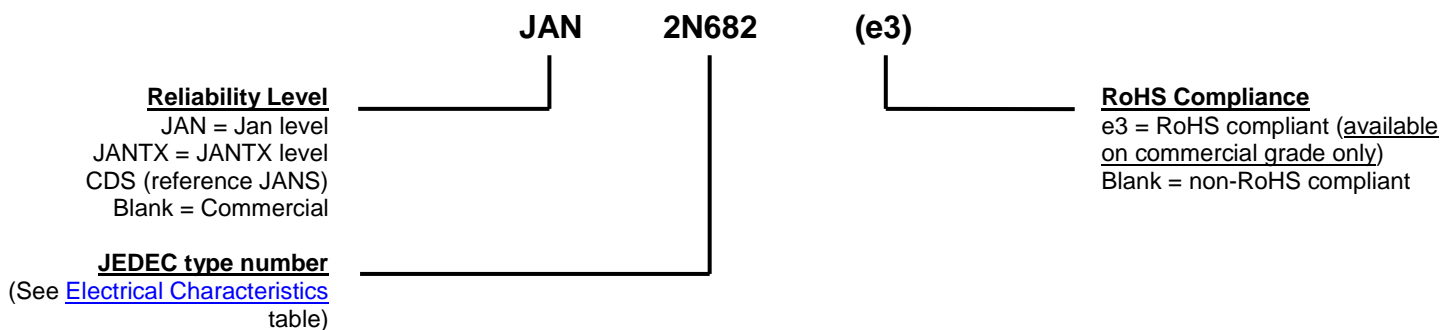
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MECHANICAL and PACKAGING

- CASE: Nickel plated copper.
- TERMINALS: Nickel plated steel, solder dipped or RoHS compliant matte-tin plating (on commercial and CDS grade only).
- MARKING: Manufacturer's ID, part number, date code, polarity.
- POLARITY: Terminal 1: gate, terminal 2: cathode, terminal 3 (stud): anode.
- WEIGHT: Approximately 12.36 grams.
- See [Package Dimensions](#) on last page.

PART NOMENCLATURE

SYMBOLS & DEFINITIONS

Symbol	Definition
C	Capacitance
di/dt	Critical rate of rise of on-state current
dv/dt	Critical rate of rise of off-state voltage
f	frequency
I _F	Forward current
I _T	On-state current
I _{TM}	On-state current (peak total value)
R	Resistance
R _e	Responsivity, radiant
R _L	Resistor load
t	time
tp	Pulse variation
V _{AA}	Anode power supply voltage (dc)

ELECTRICAL CHARACTERISTICS

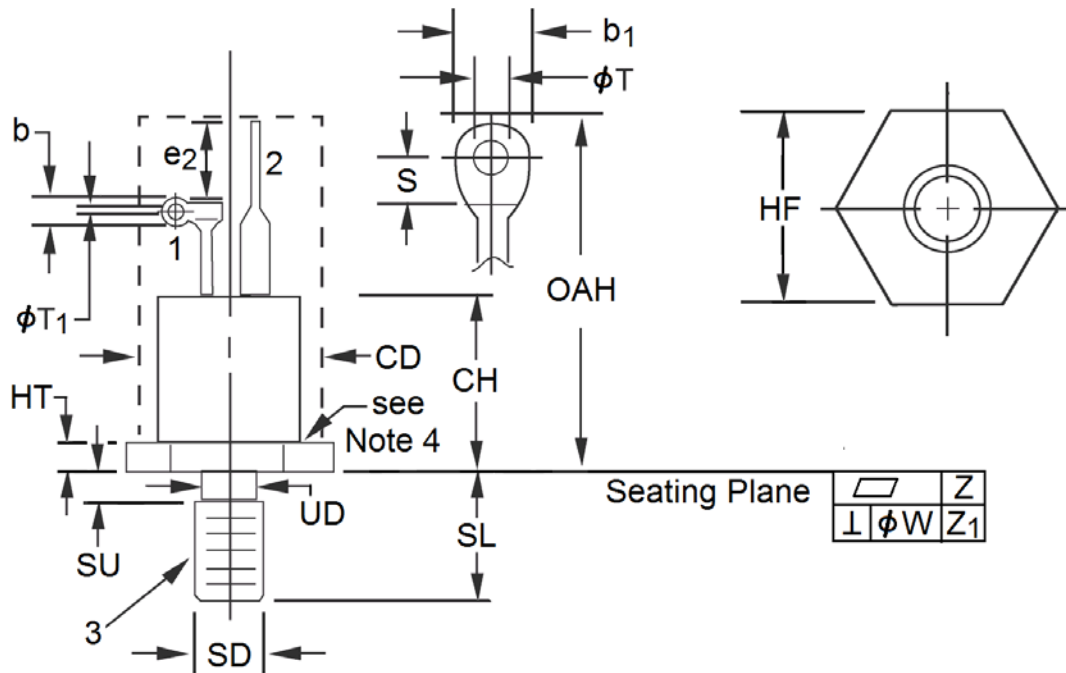
Parameters / Test Conditions	Symbol	Min.	Max.	Unit
Repetitive Peak Reverse Voltage and Repetitive Peak Off-State Voltage	$V_{RRM}^{(1)}$ and V_{DRM}		50 100 200 250 300 400 500 600 700 800	V (pk)

(1) Values applicable to zero or negative gate voltage (V_{GM}).

Parameters / Test Conditions	Symbol	Min.	Max.	Unit
Holding current: Bias condition D; $V_{AA} = 24$ V maximum; $I_{TM} = I_{F1} = 1$ A $I_T = I_{F2} = 100$ mA trigger voltage source = 10 V trigger PW = 100 μ s (minimum) $R_2 = 20 \Omega$	I_H		50	mA
Reverse blocking current AC method, bias condition D; $f = 60$ Hz, $V_{RRM} =$ rated	I_{RRM1}		2	mA (pk)
Forward blocking current AC method, bias condition D; $f = 60$ Hz; $V_{DRM} =$ rated	I_{DRM1}		2	mA (pk)
Gate trigger voltage and current $V_2 = V_D = 6$ V; $R_L = 50 \Omega$; $R_e = 20 \Omega$ maximum	V_{GT1} I_{GT1}		3 35	V mA
Forward on voltage $I_{TM} = 50$ A(pk) (pulse); pulse width = 8.5 ms; maximum; duty cycle = 2 percent maximum	V_{TM}		2	V (pk)
Reverse gate current $V_G = 5$ V	I_G		250	mA

ELECTRICAL CHARACTERISTICS (continued)

Parameters / Test Conditions	Symbol	Min.	Max.	Unit
Reverse blocking current ($T_C = +120\text{ }^\circ\text{C}$) AC method, bias condition D; $f = 60\text{ Hz}$; $V_{RRM} = \text{rated}$	I_{RRM2}		5	mA (pk)
Forward blocking current ($T_C = +120\text{ }^\circ\text{C}$) AC method, bias condition D; $f = 60\text{ Hz}$; $V_{DRM} = \text{rated}$	I_{DRM2}		5	mA (pk)
Gate trigger voltage ($T_C = +120\text{ }^\circ\text{C}$; $R_e = 20\text{ }\Omega$ max) $V_2 = V_{DM} = 50\text{ V}$; $R_L = 140\text{ }\Omega$ 2N682 $V_2 = V_{DM} = 100\text{ V}$; $R_L = 140\text{ }\Omega$ 2N683 $V_2 = V_{DM} = 200\text{ V}$; $R_L = 140\text{ }\Omega$ 2N685 $V_2 = V_{DM} = 250\text{ V}$; $R_L = 650\text{ }\Omega$ 2N686 $V_2 = V_{DM} = 300\text{ V}$; $R_L = 650\text{ }\Omega$ 2N687 $V_2 = V_{DM} = 400\text{ V}$; $R_L = 3\text{ k}\Omega$ 2N688 $V_2 = V_{DM} = 500\text{ V}$; $R_L = 3\text{ k}\Omega$ 2N689 $V_2 = V_{DM} = 600\text{ V}$; $R_L = 3\text{ k}\Omega$ 2N690 $V_2 = V_{DM} = 700\text{ V}$; $R_L = 3\text{ k}\Omega$ 2N691 $V_2 = V_{DM} = 800\text{ V}$; $R_L = 3\text{ k}\Omega$ 2N692	V_{GT2}	.25		V
Reverse blocking current ($T_C = -65\text{ }^\circ\text{C}$) AC method, bias condition D; $f = 60\text{ Hz}$; $V_{RRM} = \text{rated}$	I_{RRM3}		2	mA (pk)
Forward blocking current ($T_C = -65\text{ }^\circ\text{C}$) AC method, bias condition D; $f = 60\text{ Hz}$; $V_{DRM} = \text{rated}$	I_{DRM3}		2	mA (pk)
Gate trigger voltage and current ($T_C = -65\text{ }^\circ\text{C}$) $V_2 = V_D = 6\text{ V}$; $R_L = 50\text{ }\Omega$; $R_e = 20\text{ }\Omega$ maximum	V_{GT3} I_{GT2}		3 80	V mA
Exponential rate of voltage rise Bias condition D; $T_C = +120\text{ }^\circ\text{C}$ minimum, $dv/dt = 25\text{ v}/\mu\text{s}$; repetition rate = 60 pps; test duration = 15 s; $C = 1.0\text{ }\mu\text{F}$; $R_L = 50\text{ }\Omega$ $V_{AA} = 50\text{ V}$ 2N682 $V_{AA} = 100\text{ V}$ 2N683 $V_{AA} = 200\text{ V}$ 2N685 $V_{AA} = 250\text{ V}$ 2N686 $V_{AA} = 300\text{ V}$ 2N687 $V_{AA} = 400\text{ V}$ 2N688 $V_{AA} = 500\text{ V}$ 2N689 $V_{AA} = 600\text{ V}$ 2N690 $V_{AA} = 700\text{ V}$ 2N691 $V_{AA} = 800\text{ V}$ 2N692	V_D		47 95 190 240 285 380 475 570 665 760	V

PACKAGE DIMENSIONS

NOTES:

1. Dimensions are in inches. Millimeters are given for information only.
2. Device contour, except on hex head and noted terminal dimensions, is optional within zone defined by CD and OAH, CD not to exceed actual HF.
3. Contour and angular orientation of terminals 1 and 2 with respect to hex portion and to each other are optional.
4. Chamfer or undercut on one or both ends of the hexagonal portion are optional.
5. Square or radius on end of terminal is optional.
6. Minimum difference in terminal lengths to establish datum line for numbering terminals.
7. Dimension SD is pitch diameter of coated threads.
8. In accordance with ASME Y14.5M, diameters are equivalent to Φ x symbology.

Ltr	Dimensions				Notes
	Inches		Millimeters		
	Min	Max	Min	Max	
b	0.115	0.139	2.92	3.53	3
b1	0.210	0.300	5.33	7.62	3
CD	-	0.543	-	13.8	2
CH	-	0.550	-	14.00	
e2	0.125	-	3.17	-	6
HF	0.544	0.563	13.8	14.3	
HT	0.075	0.200	1.9	5.08	4
OAH	-	1.193	-	30.3	2
S	0.120	-	3.05	-	3
SD	¼ - 28 UNF 2A				
SL	0.422	0.453	10.7	11.5	
SU	-	0.090	-	2.29	
ΦT	0.125	0.165	3.17	4.19	
ΦT1	0.060	0.075	1.52	1.9	
UD	0.220	0.249	5.59	6.32	

Terminal 1	Gate	
Terminal 2	Cathode	5
Terminal 3	Anode (Stud)	7